

L Number	Hits	Search Text	DB	Time stamp
5	55526	metal with wire	USPAT; US-PGPUB	2001/11/03 17:57
6	25439	(metal with wire) and (insulat\$3 dielectric)	USPAT; US-PGPUB	2001/11/03 17:57
7	2062	((metal with wire) and (insulat\$3 dielectric)) and (glass with substrate)	USPAT; US-PGPUB	2001/11/03 17:58
8	926	((metal with wire) and (insulat\$3 dielectric)) and (glass with substrate)) and (semiconductor with (chip substrate))	USPAT; US-PGPUB	2001/11/03 17:23
9	901	((metal with wire) and (insulat\$3 dielectric)) and (glass with substrate)) and (semiconductor with (chip substrate))) and (contact via hole open\$4)	USPAT; US-PGPUB	2001/11/03 17:58
10	58366	metal with wire	EPO; JPO; DERWENT; IBM TDB	2001/11/03 17:57
11	12121	(metal with wire) and (insulat\$3 dielectric)	EPO; JPO; DERWENT; IBM TDB	2001/11/03 17:58
12	142	((metal with wire) and (insulat\$3 dielectric)) and (glass with substrate)	EPO; JPO; DERWENT; IBM TDB	2001/11/03 17:58
13	54	((metal with wire) and (insulat\$3 dielectric)) and (glass with substrate)) and (contact via hole open\$4)	EPO; JPO; DERWENT; IBM TDB	2001/11/03 17:59